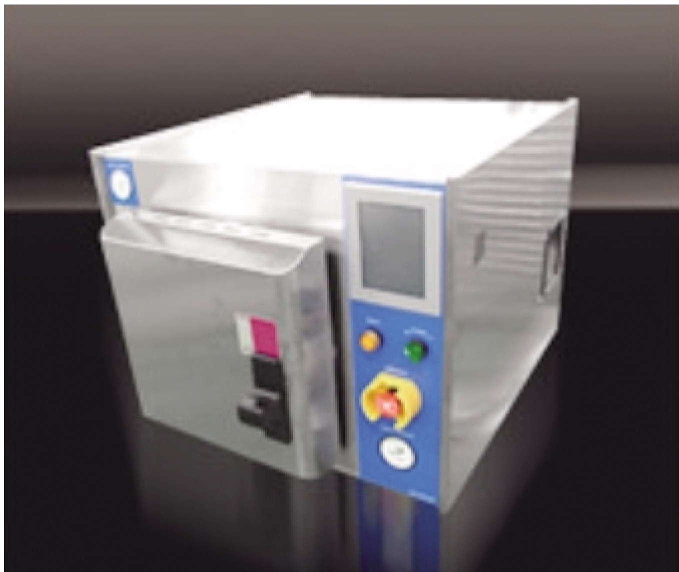
Adwill®
will give you the Advantage

Pressurized Curing System

RAD-9100-050



Outline

–Pressurized curing system used for Adwill LE Tape for substrates. The heat and pressure curing reduces voids from occuring between Adwill LE Tape and substrate, thus improving die bonding reliability. This system eliminates the substrate baking process prior to die bonding.

Suitable Tape ·Dicing die bonding tape : Adwill LE Tape

Facility

Power Supply	Voltage	: AC100V
	Frequency	: 50/60Hz
	Phase	: single phase
	Power consumption	: 1.0kW
Air Supply	Air pressure	: 0.98MPa
	Air consumption	: >11.2L/cycle

Applicable Wafer Size

N/A

Size

Width : 670mm
Depth : 825mm
Height : 556mm

Weight

121kg

Effective Height

Max. 158mm

Maximum Pressure

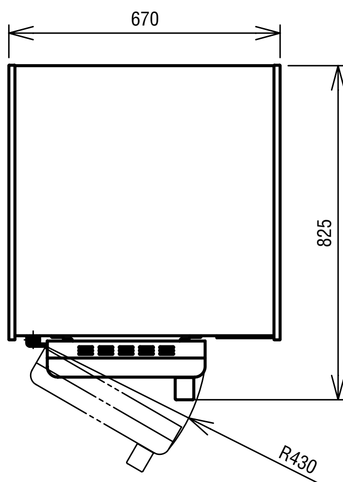
1.0MPa

Maximum Temperature

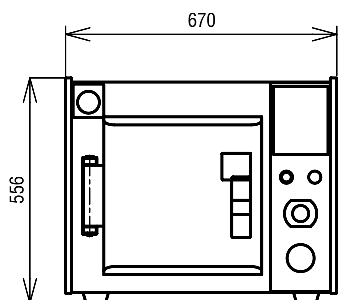
200℃

External View

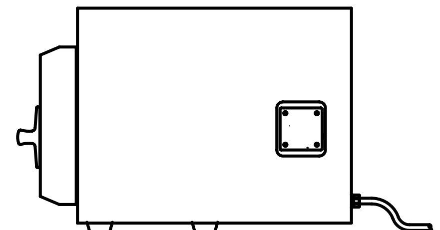
Unit:mm



Top View



Front View



Right Side View

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